

Method For Selectively Metallizing A Substrate

Abstract

5 A method for selectively metallizing, e.g., for forming an
electrical circuit on, a substrate, such as a printed circuit
board substrate, a polyimide substrate or a ceramic substrate,
is disclosed. Significantly, this method does not involve the
use of a photoresist, or of a corresponding chemical developer
or photoresist stripper. Rather, in accordance with the method,
a layer of seeding solution is formed on a substrate surface of
10 interest. This layer is exposed to light of appropriate wavelength,
through a mask, which results in the formation of metal seed on
regions of the substrate surface corresponding to the regions of
the layer of seeding solution exposed to light. The unexposed
regions of the layer of seeding solution are removed by subjecting
15 the exposed and unexposed regions of the layer of seeding solution
to an alkaline solution. Thereafter, additional metal is deposited,
e.g., plated, onto the metal seed using conventional techniques.

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